PAN30TG06G

N-Ch 30V Fast Switching MOSFET

V_{DS}=30V, I_D=90A ,$RDS_{(ON)}$=6.0mΩ

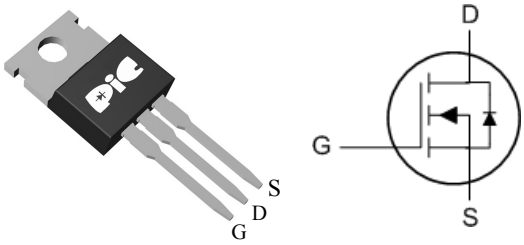
➢ General Description

This PAN30TG06G N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➢ Feature

- ●Super Low Gate Charge
- ●100% EAS Guaranteed
- ●Green Device Available
- ●Excellent CdV/dt effect decline
- ●Advanced high cell density Trench technology
- ●TO-220 package design

➢ TO-220



➢ Application

- ●SMPS Power Supplier.
- ●Charger Adapter
- ●Power Tools
- ●LED Lighting

➢ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_C=25℃	90	A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_C=100℃	58	A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_A=25℃	15	A
Continuous Drain Current, V_{GS} @ 10V[1]	I_D@T_A=70℃	12	A
Pulsed Drain Current[2]	I_{DM}	180	A
Single Pulse Avalanche Energy[3]	EAS	115	mJ
Avalanche Current	I_{AS}	48	A
Total Power Dissipation[4]	P_D@T_C=25℃	74	W
Total Power Dissipation[4]	P_D@T_A=25℃	2	W
Storage Temperature Range	T_{STG}	-55 to 150	℃
Operating Junction Temperature Range	T_J	-55 to 150	℃
Thermal Resistance Junction-ambient (Steady State)[1]	$R_{\theta JA}$	62	℃/W
Thermal Resistance Junction-Case[1]	$R_{\theta JC}$	1.68	℃/W

➢ Electrical Characteristics (T_J =25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V , I_D=250uA	30	---	---	V
BVDSS Temperature Coefficient	Δ BV_{DSS}/Δ T_J	Reference to 25℃ , I_D=1mA	---	0.028	---	V/℃
Static Drain-Source On-Resistance2	$R_{DS(ON)}$	V_{GS}=10V , I_D=30A	---	---	6	mΩ
		V_{GS}=4.5V , I_D=15A	---	---	9	
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS} , I_D =250uA	1.2	---	2.5	V
$V_{GS(th)}$ Temperature Coefficient	Δ $V_{GS(th)}$		---	-6.16	---	mV/℃
Drain-Source Leakage Current	I_{DSS}	V_{DS}=24V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55℃	---	---	5	
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
Forward Transconductance	gfs	V_{DS}=5V , I_D=30A	---	43	---	S
Gate Resistance	R_g	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.6	---	Ω
Total Gate Charge (4.5V)	Q_g	V_{DS}=15V , V_{GS}=4.5V , I_D=15A	---	20	---	nC
Gate-Source Charge	Q_{gs}		---	7.6	---	
Gate-Drain Charge	Q_{gd}		---	7.2	---	
Turn-On Delay Time	$T_{d(on)}$	V_{DD}=15V , V_{GS}=10V , R_G=3.3ΩI_D=15A	---	7.8	---	ns
Rise Time	T_r		---	15	---	
Turn-Off Delay Time	$T_{d(off)}$		---	37.3	---	
Fall Time	T_f		---	10.6	---	
Input Capacitance	C_{iss}	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	2295	---	pF
Output Capacitance	C_{oss}		---	267	---	
Reverse Transfer Capacitance	C_{rss}		---	210	---	

➢ Guaranteed Avalanche Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Single Pulse Avalanche Energy5	EAS	V_{DD}=25V , L=0.1mH , I_{AS}=24A	63	---	---	mJ

➢ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current1,5	I_S	V_G=V_D=0V , Force Current	---	---	90	A
Pulsed Source Current2,5	I_{SM}		---	---	180	A
Diode Forward Voltage2	V_{SD}	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
Reverse Recovery Time	t_{rr}	I_F=30A , dI/dt=100A/μs , T_J=25℃	---	14	---	nS
Reverse Recovery Charge	Q_{rr}		---	5	---	nC

Note :

1.Pulse width limited by maximum junction temperature.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=48A

4.Ensure that the channel temperature does not exceed 150°C.

5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

➢ Typical Characteristics

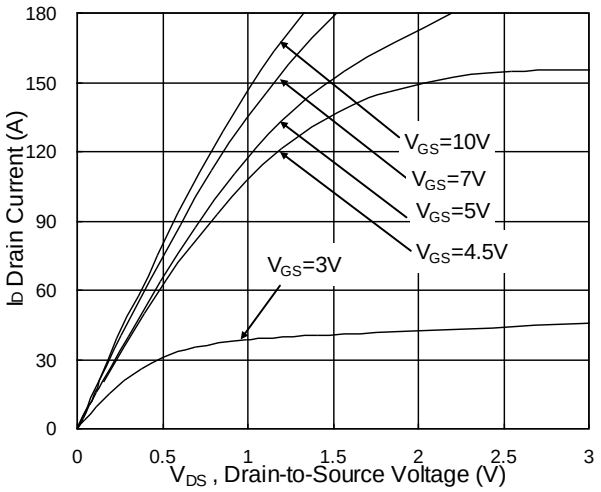


Fig.1 Typical Output Characteristics

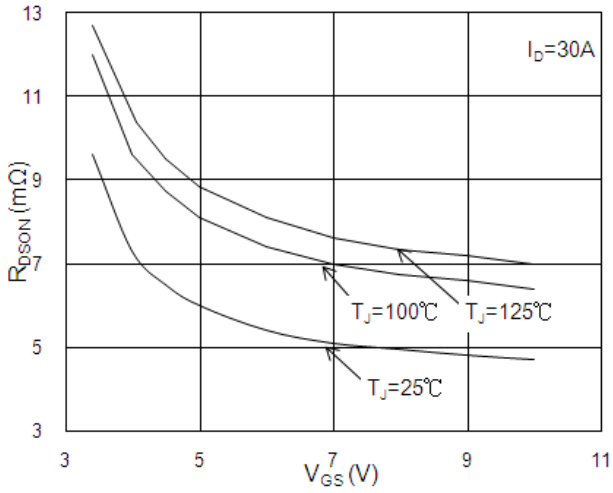


Fig.2 On-Resistance vs. G-S Voltage

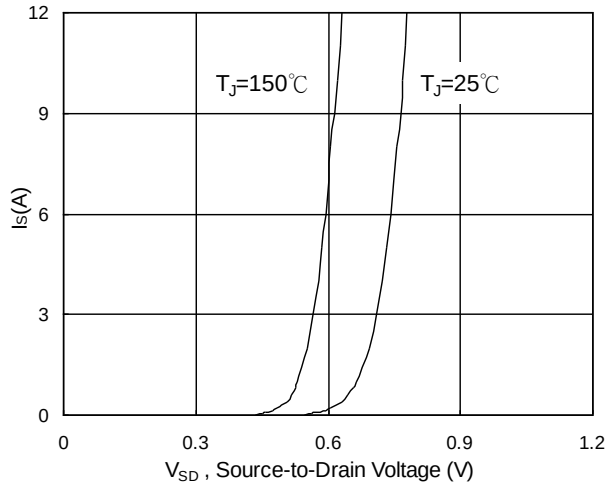


Fig.3 Forward Characteristics of Reverse

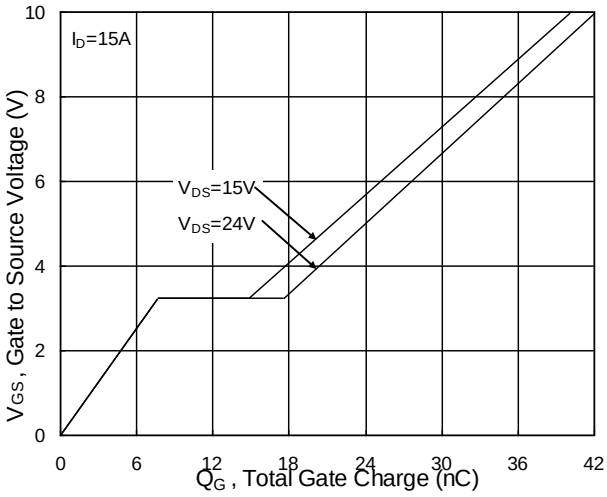


Fig.4 Gate-Charge Characteristics

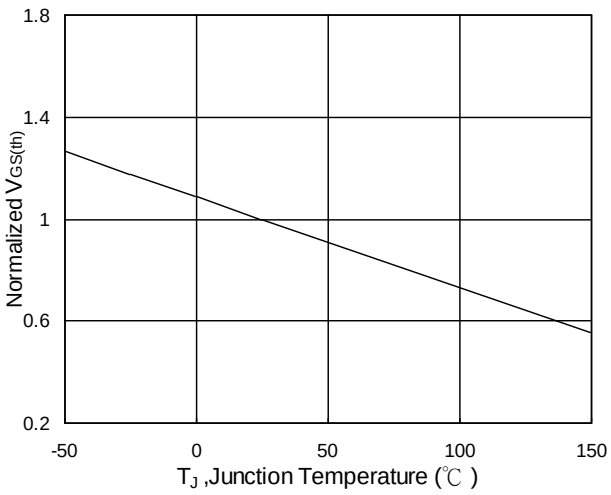


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

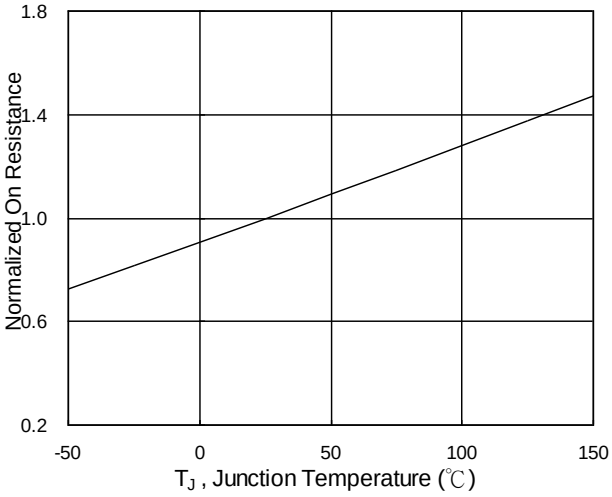


Fig.6 Normalized R_{DSON} vs. T_J

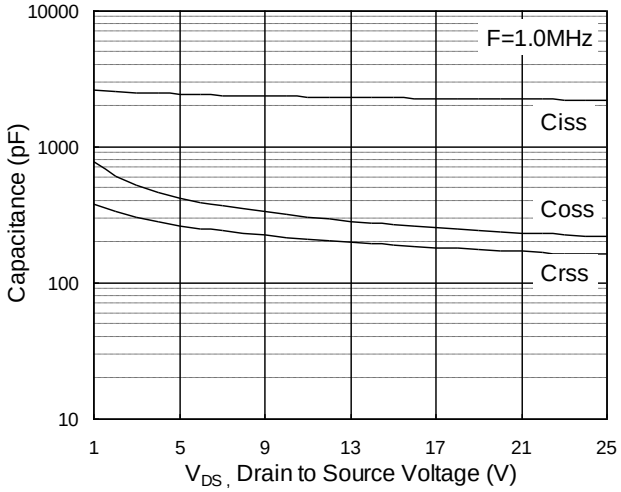


Fig.7 Capacitance

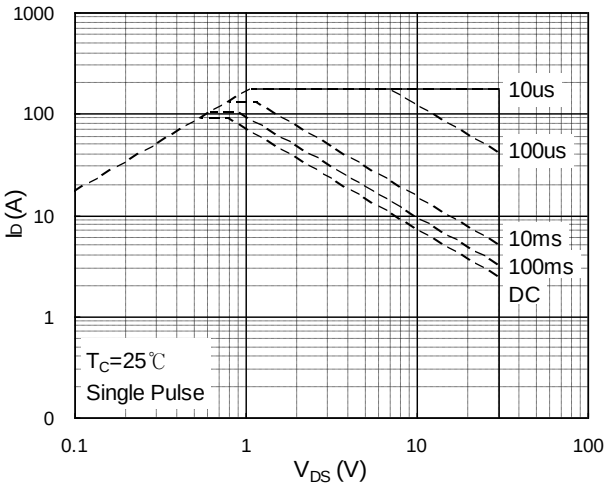


Fig.8 Safe Operating Area

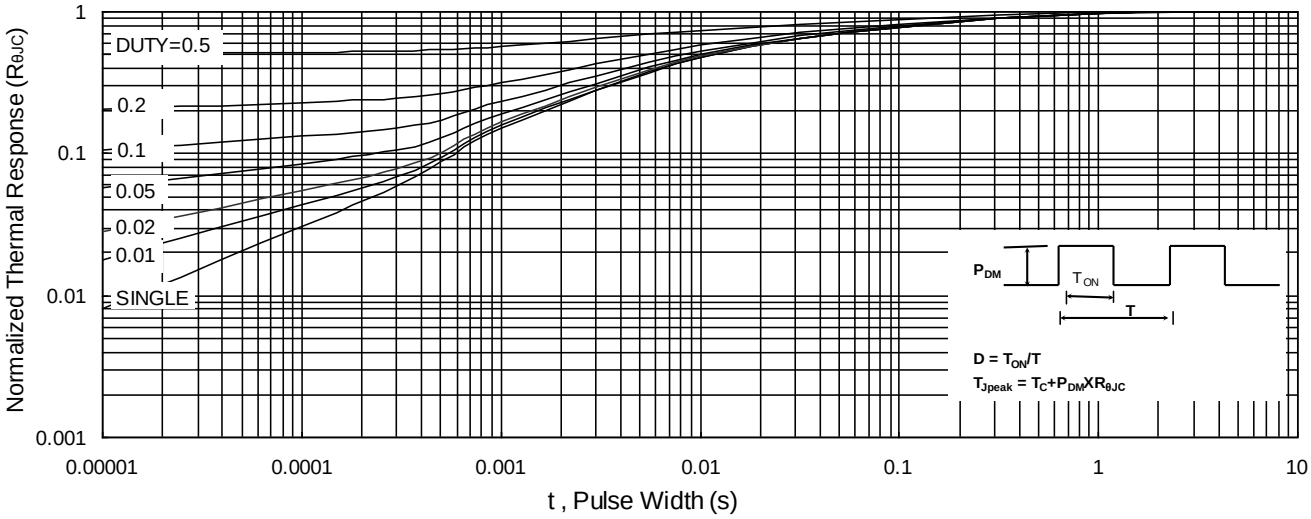


Fig.9 Normalized Maximum Transient Thermal Impedance

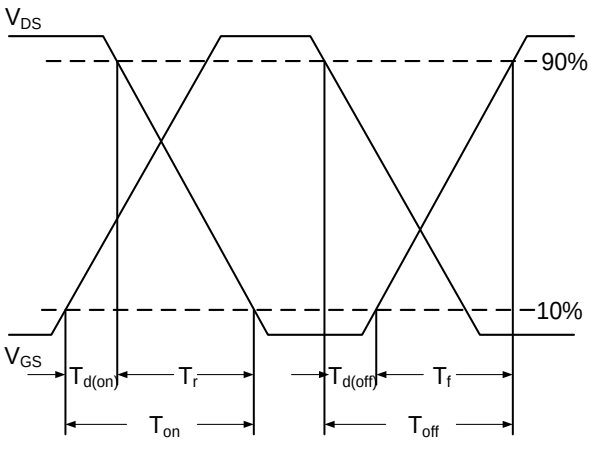


Fig.10 Switching Time Waveform

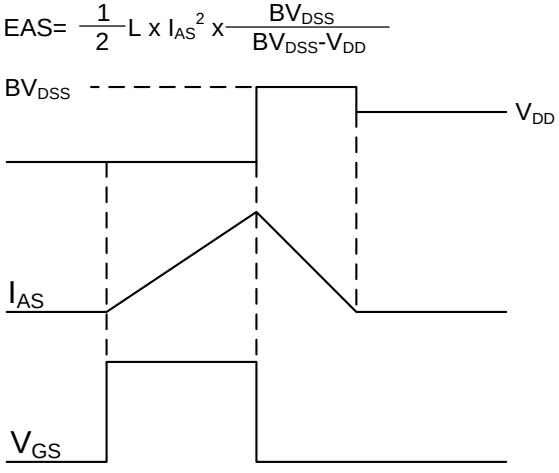
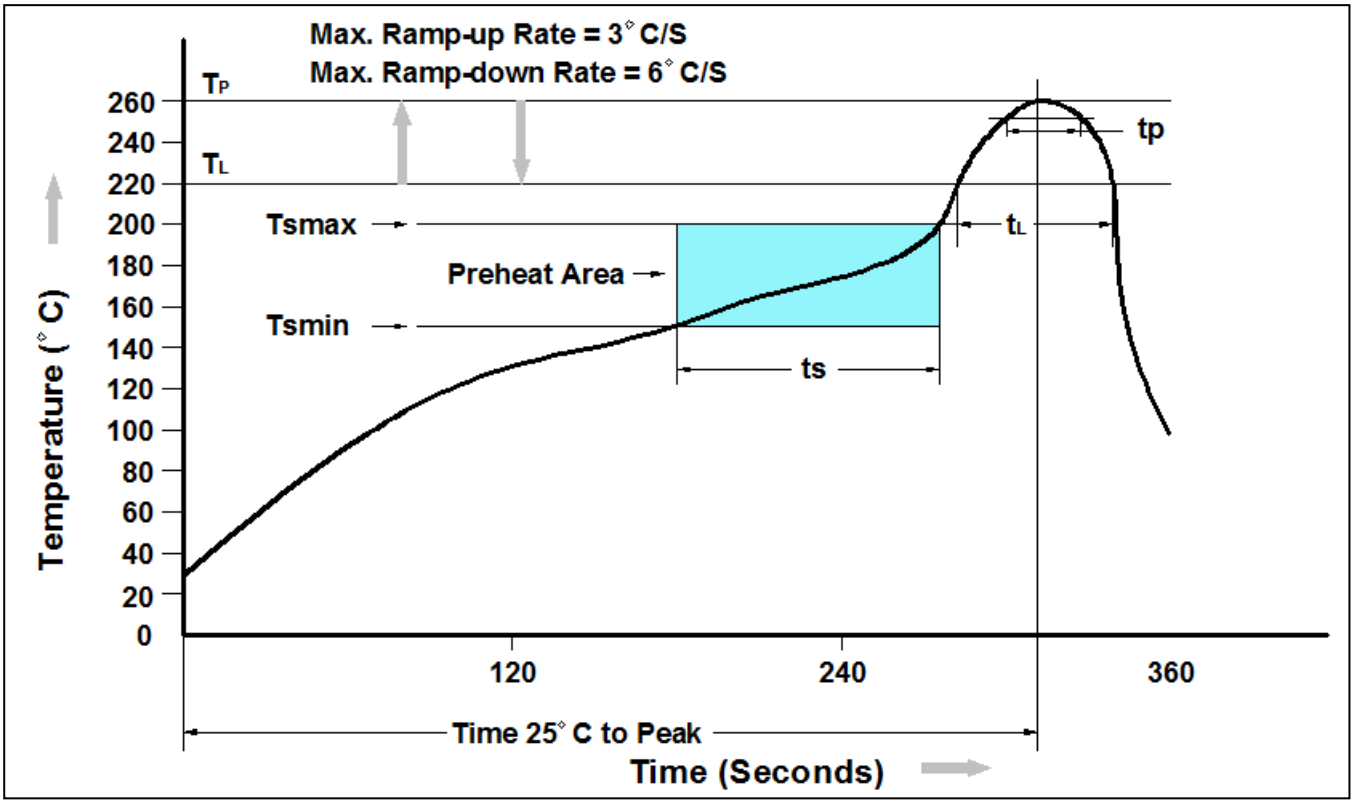


Fig.11 Unclamped Inductive Switching Waveform

➢ Recommand IR Reflow Soldering Thermal Profile

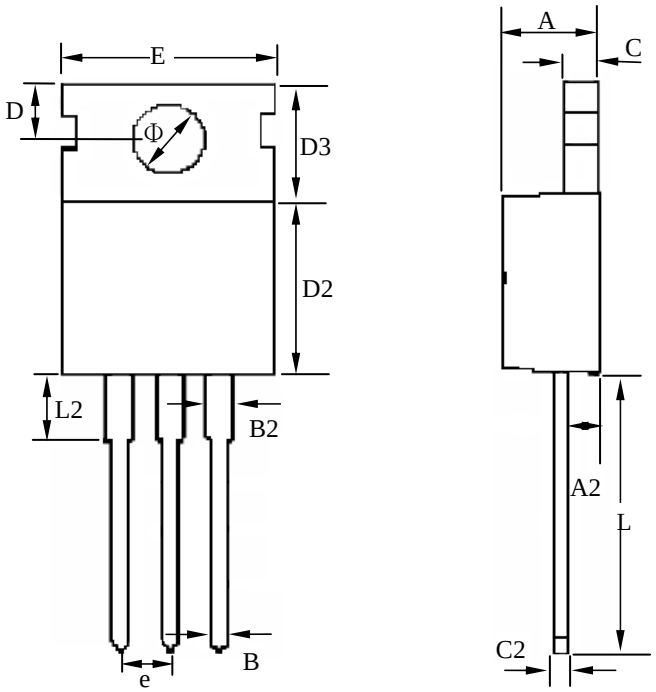


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➢ Ordering Information

Part Number	Description	Quantity
PAN30TG06G	TO-220	50 pcs/tube

➢ Package Information (TO-220)



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.25	--	4.80	0.167	--	0.189
A2	2.20	--	2.92	0.087	--	0.115
B	0.70	--	0.91	0.028	--	0.036
B2	1.15	--	1.77	0.045	--	0.070
C	1.20	--	1.40	0.047	--	0.055
C2	0.45	--	0.61	0.018	--	0.024
D	2.54	--	3.00	0.100	--	0.118
D2	8.39	--	9.47	0.330	--	0.373
D3	6.30	--	6.70	0.248	--	0.264
E	9.70	--	10.36	0.382	--	0.408
L	12.75	--	14.40	0.502	--	0.567
L2	2.45	--	4.05	0.096	--	0.159
Φ	3.50	--	3.80	0.138	--	0.150
e	--	2.54	--	--	0.100	--

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